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Bib Data Sheet

**CONFIRMATION NO. 8533** 

SERIAL NUMBER 10/529,742	FILING OR 371(c)  DATE  01/06/2006  RULE  CLAS  438		L <b>ASS</b> 438	GROUP ART UNIT 1765			ATTORNEY DOCKET NO. 268844USOPCT	
Nobuo Kawahas  ** CONTINUING DATA  This application  ** FOREIGN APPLICA			CC					
iso uote i 19 (a-a) conditions i i i i i i i i i i i i i i i i i i i			STATE OR COUNTRY JAPAN	SHEETS TOTAL CLAI		MS	INDEPENDENT CLAIMS 3	
ADDRESS 22850								
TITLE Polishing pad for semi- method for polishing so	conductor wafer, polish emiconductor wafer	ing multila	ayered body f	or sem	iconduc	ctor wafe	r havi	ng same, and
RECEIVED No	FEES: Authority has been given in Paper No to charge/credit DEPOSIT ACCOUNT No for following:				☐ All Fees ☐ 1.16 Fees ( Filing ) ☐ 1.17 Fees ( Processing Ext. of time ) ☐ 1.18 Fees ( Issue ) ☐ Other ☐ Credit			